Serial Number: 10/756,901 Filing Date: January 14, 2004

Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

Dkt: 303.572US2

IN THE SPECIFICATION

Please amend the paragraph beginning on page 1, line 4 with the following rewritten paragraph:

This application is a divisional of U.S. Application No. 09/253,611 filed on February 19, now U.S. Patent No. 6,844,253, and is incorporated herein by reference.